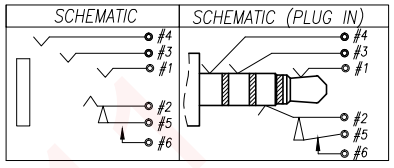
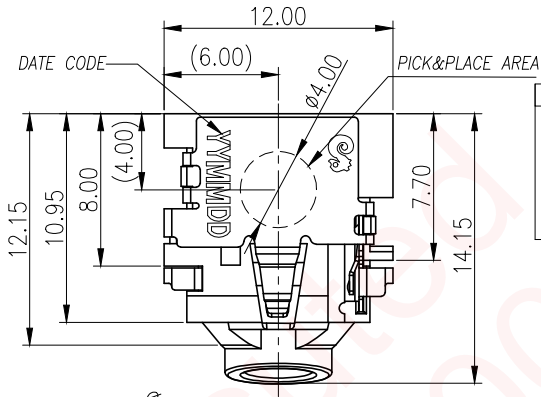
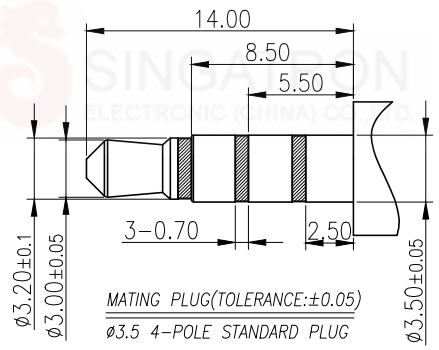
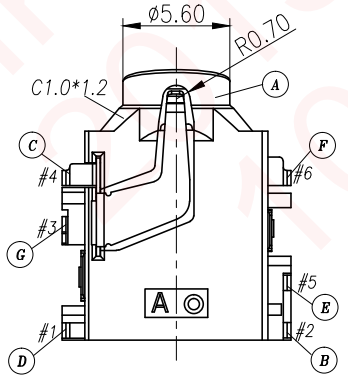
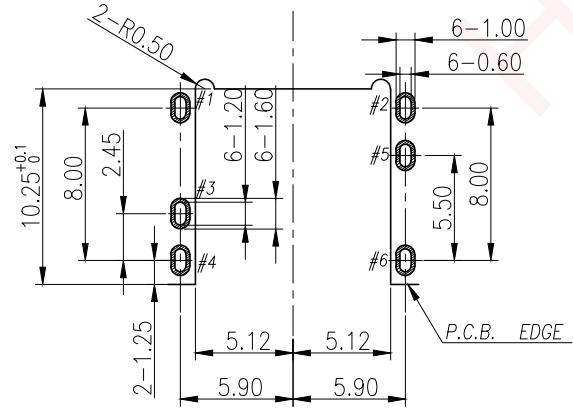
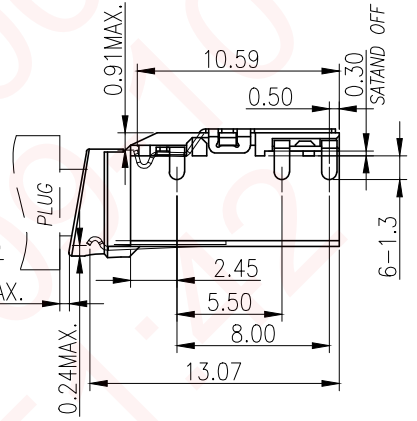
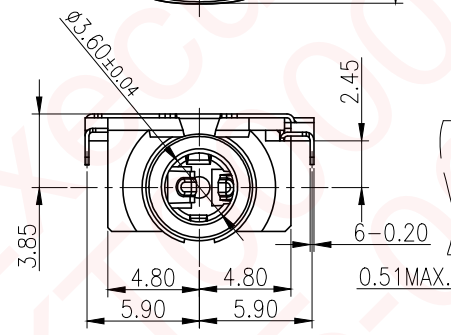
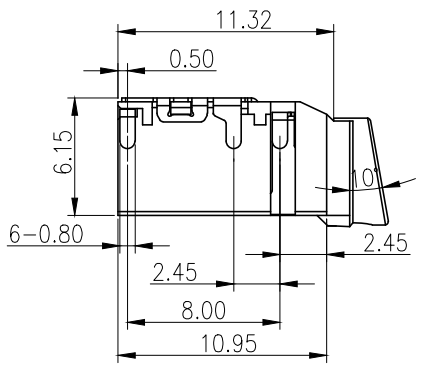


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: T140915-1A	ROBIN	2015.08.31



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC .
  - CONTACT RESISTANCE: 50mΩ MAX.
  - INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
  - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
  - LIFE TEST: 5,000 CYCLES.
  - INSERTION FORCE: 0.3 - 3.0Kg.
  - WITHDRAWAL FORCE: 0.3 - 3.0Kg.
  - AFTER TEST, CONTACT RESISTANCE: 100mΩ MAX.
  - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
  - MARKING: MARK "S" ON TOP OF CONNECTOR.
  - PACKING : TAPE & REEL.
  - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
  - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:
  - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:



G	SHIELDING	1	COPPER ALLOY, 0.2t	ALL NI(电鍍) 60u" MIN.
F	MAKE	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA; GOLD FLASH ON SOLDER AREA; ALL OVER 50u" Ni.
E	TRANSFER	1	COPPER ALLOY, 0.2t	
D	TIP	1	COPPER ALLOY, 0.2t	Pd/Ni (30u" MIN.)&GOLD PLATED(5u" MIN.)
C	EARTH	1	COPPER ALLOY, 0.2t	ON CONTACT AREA; MATTE SN 120u" MIN.
B	RING SPRING &SEPARATOR	1	COPPER ALLOY, 0.2t HIGH TEMP.THERMOPLASTIC UL 94V-0	ON SOLDER TAIL; ALL OVER Ni 50u" MIN. BLACK
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.  
 信音企業股份有限公司

DECIMALS:	ANGLES:	TITLE	3.5Ø PHONE JACK		
X :±0.5	X :±2°	DWN	ROBIN	PART NO.2SJ3086-014111F	
X.X :±0.3	X.X :±1°	CHKD	Bruce	SCALE: 4:1	UNIT: mm
X.XX :±0.2		APVD	Lussen	SIZE: A3	SHEET: 1 OF 1
REV: A					

CUSTOMER COPY